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Nextreme's miniature thin film eTEC™ recognized as a 2007 Product of the Year...

NEXTREME HONORED BY ELECTRONIC PRODUCTS WITH 2007 PRODUCT OF THE YEAR AWARD

DURHAM, N.C. (March 31, 2008) — Nextreme Thermal Solutions™, the leader in microscale thermal and power management products for the electronics industry, has received a 2007 Product of the Year award from Electronic Products Magazine for its miniature, thin-film embedded thermoelectric component (eTEC™) technology. The award was presented during a ceremony at Nextreme's new manufacturing and R&D facility in Durham, NC.



“The Product of the Year award was established to identify and reward products that are innovative in their design, represent a significant advancement in a technology or its application, and display a substantial achievement in the price and/or performance of the device,” said Ralph Raiola, Electronic Products editor.

With thin-film thermal bump technology at its core, Nextreme's products can achieve temperature differentials of up to 50°C at room temperature. This achievement compares favorably with the performance of conventional thermoelectric technology, which is physically larger and unlike the thermal bump, cannot be integrated directly into the electronic packaging process. Nextreme devices employ proprietary materials that are 5–15µm thick, about 100 times thinner than the typical 1mm thick pellets used in conventional thermoelectric devices.

Adding as little as 100 microns (0.1mm) of thickness to a heat spreader or package, a reliable eTEC can be seamlessly integrated close to the heat source. The eTEC's ultra-fast, millisecond response time rapidly cools or heats to maintain a precise temperature depending on the needs of the application. Heat fluxes of $>150\text{W}/\text{cm}^2$ have been demonstrated versus $10\text{--}20\text{ W}/\text{cm}^2$ for typical bulk TECs.

"We are honored to receive a 2007 Product of the Year award from Electronic Products for our miniature thin film eTEC™ technology," said Jesko von Windheim, CEO at Nextreme. "This award recognizes our commitment to new products that address serious thermal management issues in the electronics, telecommunications, medical, industrial and aerospace & defense industries."

For more information, contact Nextreme at 3908 Patriot Drive, Durham, NC 27703; call +1 919-597-7300; e-mail info@nextreme.com; or go to www.nextreme.com.

About Nextreme Thermal Solutions, Inc.

Nextreme Thermal Solutions designs and manufactures microscale thermal and power management products that provide chip, module and system-level solutions for the semiconductor, photonics, consumer, automotive and defense/aerospace industries. The company has developed embedded cooling and power generation capabilities for the widely accepted copper pillar bumping process used in high-volume electronic packaging. Nextreme's breakthrough addresses the most challenging thermal and power management constraints in electronics today, and delivers the only fully-scalable technology solution by leveraging the existing, high-volume flip chip manufacturing infrastructure. By minimizing the need for manufacturing changes and focusing on developing a seamless design-in solution, Nextreme will change the future of thermal and power management for the entire electronics industry.

Nextreme is managed by an experienced start-up team and world-renowned experts in electronics, thermal management and pillar bump technology. The company has 38 employees and is based in Research Triangle Park, North Carolina.

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